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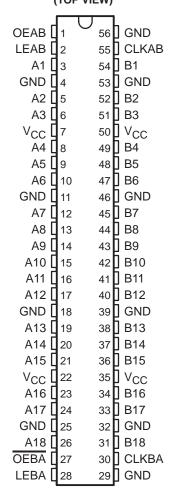
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- Members of the Texas Instruments Widebus™ Family
- B-Port Outputs Have Equivalent 25-Ω
   Series Resistors, So No External Resistors
   Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- UBT<sup>™</sup> (Universal Bus Transceiver)
   Combines D-Type Latches and D-Type
   Flip-Flops for Operation in Transparent,
   Latched, or Clocked Mode
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   < 0.8 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Impedance State During Power Up and Power Down
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### description

These 18-bit universal bus transceivers consist of storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

SN54ABT162501...WD PACKAGE SN74ABT162501...DGG OR DL PACKAGE (TOP VIEW)



Data flow in each direction is controlled by output-enable (OEAB and  $\overline{\text{OEBA}}$ ), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses  $\overline{\text{OEBA}}$ , LEBA, and CLKBA. The output enables are complementary (OEAB is active high and  $\overline{\text{OEBA}}$  is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.



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### SN54ABT162501, SN74ABT162501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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#### description (continued)

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT162501 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT162501 is characterized for operation from –40°C to 85°C.

#### **FUNCTION TABLET**

	OUTPUT			
OEAB	LEAB	CLKAB	Α	В
L	Х	Х	Χ	Z
Н	Н	Χ	L	L
Н	Н	Χ	Н	Н
Н	L	$\uparrow$	L	L
Н	L	$\uparrow$	Н	Н
Н	L	Н	Χ	в <sub>0</sub> ‡ в <sub>0</sub> §
Н	L	L	Χ	В <sub>0</sub> §

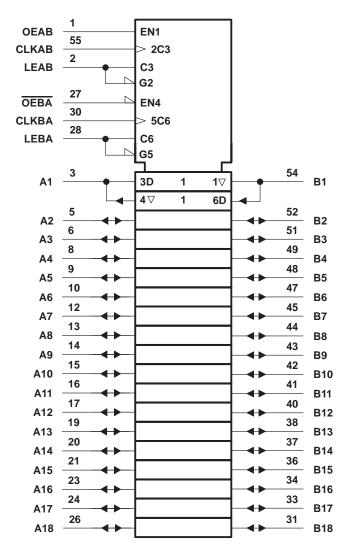
<sup>†</sup> A-to-B data flow is shown: B-to-A flow is similar but uses  $\overline{\text{OEBA}}$ , LEBA, and CLKBA.



<sup>&</sup>lt;sup>‡</sup>Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

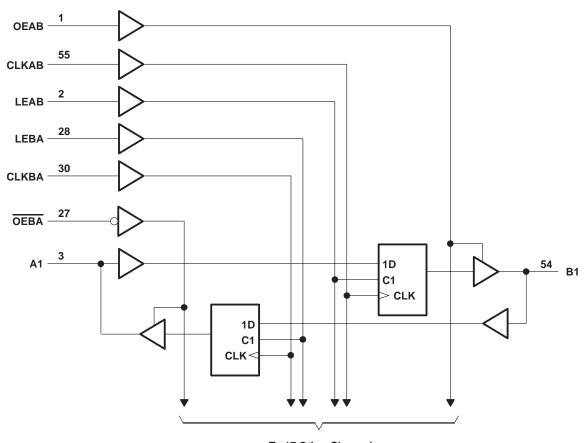
<sup>§</sup> Output level before the indicated steady-state input conditions were established

## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)



To 17 Other Channels

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT162501 (A port)	96 mA
SN74ABT162501 (A port)	128 mA
B port	30 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51.

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### recommended operating conditions (see Note 3)

			SN54ABT	162501	SN74ABT	162501	UNIT
			MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	VCC	0	Vcc	V	
la	High-level output current	A port		-24		-32	mA
Іон	B)	B port	4	-12		-12	
la.	Low lovel output ourropt	A port	200	48		64	^
lOL	Low-level output current	B port	200	12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q"	10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## SN54ABT162501, SN74ABT162501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

V <sub>I</sub> V <sub>I</sub> V <sub>C</sub> = 4.5 V,	DA	DAMETED	TEST CONDITIONS		Т	A = 25°C	;	SN54ABT162501		SN74ABT162501		UNIT	
$ \begin{tabular}{l l l l l l l l l l l l l l l l l l l $	PA	RAWEIER	lesi (	CNDITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
$\begin{array}{llllllllllllllllllllllllllllllllllll$	VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
$\begin{array}{llllllllllllllllllllllllllllllllllll$			$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
$\begin{array}{c c c c c c c c c c c c c c c c c c c $		A port	V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3			
VOH Boot   ICH = -32 mA   2"   2		A port	V 45 V	I <sub>OH</sub> = -24 mA	2			2					
Note	\/		VCC = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2		.,	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	VOH		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -1 mA	3.35			3.3		3.35		V	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		D nowt	V <sub>C</sub> C = 5 V,	$I_{OH} = -1 \text{ mA}$	3.85			3.8		3.85			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		Б роп	V = = 4 5 V	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			VCC = 4.5 V	I <sub>OH</sub> = -12 mA	2.6					2.6			
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		A port	V00 - 4 5 V	I <sub>OL</sub> = 48 mA			0.55		0.55				
$ \begin{array}{ c c c c c c c c } \hline V_{hys} & & & & & & & & & & & & & & & & & & &$	VOL	A port	VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		B port	$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 12 mA			0.8		0.8		0.8		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	V <sub>hys</sub>					100			N.			mV	
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$		Control inputs	$V_{CC} = 0 \text{ to } 5.5$	$V, V_I = V_{CC} \text{ or GND}$			±1		±1		±1		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	l <sub>l</sub>	A or B ports					±20	10	±20		±20	μΑ	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	lozpu						±50	7790	±50		±50	μΑ	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	lozpd		V <sub>CC</sub> = 2.1 V to V <sub>O</sub> = 0.5 V to 2	0, .7 V, <del>OE</del> or OE = X§			±50	Q	±50		±50	μΑ	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	lozh‡		$\frac{\text{V}_{\text{CC}}}{\text{OE}} = 2.1 \text{ V to}$ $\text{OE} \ge 2 \text{ V or OE}$	5.5 V, V <sub>O</sub> = 2.7 V, ≤ 0.8 V			10		10		10	μΑ	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>OZL</sub> ‡						-10		-10		-10	μΑ	
$ \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	l <sub>off</sub>		V <sub>CC</sub> = 0,	V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V			±100				±100	μΑ	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		Outputs high	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 5.5 V			50		50		50	μΑ	
		A port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-110	-180	-50	-180	-50	-180	^	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	IOI	B port	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-25	-55	-90	-25	-90	-25	-90	mA	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				Outputs high			3		3		3		
	ICC	A or B ports		Outputs low			36		36		36	mA	
$\triangle ICC''$ Other inputs at V <sub>CC</sub> or GND $\bigcirc$ 00 $\bigcirc$				Outputs disabled			3		3		3		
	ΔI <sub>CC</sub> #					50		50		50	μА		
	Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5		3						pF		
	C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0$	.5 V		9						pF	

 $<sup>\</sup>begin{tabular}{l}^\star$  On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup>The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

<sup>§</sup> For V<sub>CC</sub> between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.

<sup>¶</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

## timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

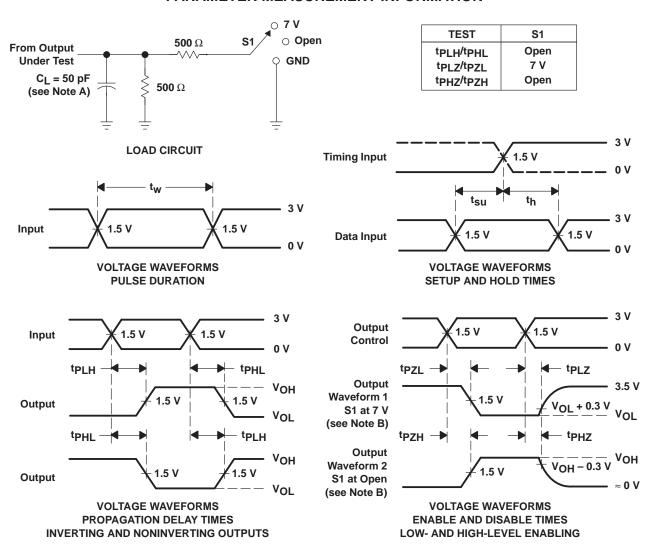
				SN54ABT	162501	SN74ABT	162501	UNIT	
				MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		150		150	MHz			
	Pulse duration	LEAB or LEBA high		3	3	3		no	
t <sub>w</sub>	Puise duration	CLKAB or CLKBA high or low	3.3	Z	3.3		ns		
		A before CLKAB↑	4.3	2	4.3				
١.	Catum time	B before CLKBA↑	4.3	,	4.3				
t <sub>su</sub>	Setup time		CLK high	2.5		2.5		ns	
		A before LEAB↓ or B before LEBA↓  CLK low		0 1		1			
	Hold time	A after CLKAB↑ or B after CLKBA↑		0		0		20	
l t <sub>h</sub>	HOIU IIIIIE	A after LEAB↓ or B after LEBA↓	2		2	·	ns		

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT162501		SN74ABT162501		UNIT
	(INTOT)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150	200		150		150		MHz
<sup>t</sup> PLH	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
t <sub>PHL</sub>	AUID	B or A	2	3.4	5.2	2	6.1	2	5.7	
<sup>t</sup> PLH	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
<sup>t</sup> PHL	LEAD OF LEDA	D OF A	2	3.8	5.2	2 0	6.4	2	5.9	
<sup>t</sup> PLH	CLKAB or CLKBA	B or A	1.5	3.5	4.7	1.5	6	1.5	5.5	—l ns l
<sup>t</sup> PHL	CLKAB OF CLKBA	BULA	1.5	3.5	4.8	1.5	5.8	1.5	5.3	
<sup>t</sup> PZH	054D 05D4	B or A	1.5	3.4	4.6	1.5	5.6	1.5	5.3	ns
tpZL	OEAB or OEBA	BULA	2	3.8	4.7	2	5.6	2	5.4	115
<sup>t</sup> PHZ	OFAD as OFDA	B or A	2	4.5	5.7	2	6.9	2	6.5	nc
t <sub>PLZ</sub>	OEAB or OEBA	DUIA	1.5	3.8	5.3	1.5	6.3	1.5	5.8	ns

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{Q}$  = 50  $\Omega$ ,  $t_{f} \leq$  2.5 ns,  $t_{f} \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







1-Aug-2011

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
74ABT162501DGGRE4	ACTIVE	TSSOP	DGG	56		TBD	Call TI	Call TI	
74ABT162501DGGRG4	ACTIVE	TSSOP	DGG	56		TBD	Call TI	Call TI	
74ABT162501DLRG4	ACTIVE	SSOP	DL	56		TBD	Call TI	Call TI	
SN74ABT162501DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ABT162501DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
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Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
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